

Substitute form 1449A/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

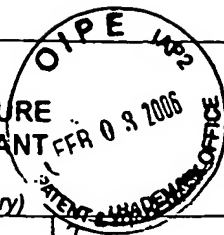
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Sheet

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of

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Complete if Known

Application Number	10/790,967
Filing Date	March 2, 2004
First Named Inventor	Glenn A. Rinne
Group Art Unit	1725
Examiner Name	Michael Aboagye
Attorney Docket Number	9180-10CT

U.S. PATENTS AND PATENT PUBLICATIONS

Examiner Initials*	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Number	Kind Code (if known)		
AM	1.	US-2001/0011764		Elenius et al.	08/2001
	2.	US-2001/0020745		Jiang et al.	09/2001
	3.	US-2001/0042918		Yanagida	11/22/2001
	4.	US-2002/0000665		Barr et al;	01/03/2002
	5.	US-2002/0056742		Rinne	05/2002
	6.	US-2002/0079576		Seshan	06/27/2002
	7.	US-2002/0086520		Chiang	07/2002
	8.	US-2002/0093098		Barr et al;	07/18/2002
	9.	US-2002/0096764		Huang	07/2002
	10.	US-2002/0197842		Kuo et al;	12/2002
	11.	US-2003/0000738		Rumsey et al	01/2003
	12.	US-2003/0060040		Lee et al;	03/27/2003
	13.	US-2003/0107137		Stierman et al;	06/2003
	14.	US-2003/0143830		Akram	07/2003
	15.	US-2003/124833		Ho-Ming et al.	07-03-2003
	16.	US-2003/143830		Salman	07-31-2003
	17.	US-2004/0053483		Nair et al;	03/2004
	18.	US-3,105,869		Branch et al;	10/1963
	19.	US-3,244,947		Slater	04/1966
	20.	US-3,259,814		Green	07/1966
	21.	US-3,274,458		Boyer et al;	09/1966
	22.	US-3,316,465		von Bermuth et al;	04/1967
	23.	US-3,458,925		Napier et al;	08/1969
	24.	US-3,461,357		Mutter et al;	08/1969
	25.	US-3,489,965		Helsdon	01/1970
	26.	US-3,501,681		Weir	03/17/1970
	27.	US-3,586,255		Mandal	10/1976
	28.	US-3,663,184		Wood et al;	05/16/1972
	29.	US-3,760,238		Hamer et al;	09/18/1973
	30.	US-3,770,874		Krieger et al;	11/06/1973
	31.	US-3,839,727		Herdzik et al.	10/01/1974
	32.	US-3,871,015		Lin et al;	03/1975
	33.	US-3,897,871		Zimnbauer	08/1975
	34.	US-3,916,080		Wakamatsu	10/1975
	35.	US-3,942,187		Gelsing et al;	03/02/1976
	36.	US-3,959,577		Frink	05/1976
	37.	US-3,986,255		Mandal	10/1976
	38.	US-3,993,123		Chu et al;	11/1976
	39.	US-4,074,342		Honn et al;	02/14/1978
	40.	US-4,113,578		Del Monte	09/12/1978
	41.	US-4,113,587		Chikamori	09/1978
	42.	US-4,168,480		De Lucia	09/1979
	43.	US-4,244,002		Sato et al;	01/1981
	44.	US-4,257,905		Christophorou et al;	03/1981
	45.	US-4,266,282		Henle et al;	05/1981
	46.	US-4,273,859		Mones et al;	06/1981
	47.	US-4,332,341		Minetti, Richard H.	06/1982
	48.	US-4,382,517		Welsch	05/1983

Examiner Signature

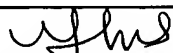
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			Filing Date	March 2, 2004	
			First Named Inventor	Glenn A. Rinne	
			Group Art Unit	1725	
			Examiner Name	Michael Aboagye	
Sheet	2	of	7	Attorney Docket Number	9180-10CT

AM	49.	US-4,449,580	Reisman et al;	05/1984
	50.	US-4,640,438	Trevison et al;	02/1987
	51.	US-4,473,263	Sunstein	09/1984
	52.	US-4,505,029	Owyang et al;	03/1985
	53.	US-4,511,873	Baier et al;	04/1985
	54.	US-4,532,576	Reimer	07/1985
	55.	US-4,545,610	Lakritz et al;	10/1985
	56.	US-4,563,697	Miura	01/1986
	57.	US-4,565,901	Hirooka et al;	01/1986
	58.	US-4,657,146	Walters	04/1987
	59.	US-4,661,375	Thomas	04/1987
	60.	US-4,673,772	Satoh et al;	06/1987
	61.	US-4,733,813	Le Meau et al;	03/1988
	62.	US-4,752,027	Oschwend	06/1988
	63.	US-4,763,829	Sherry	08/1988
	64.	US-4,783,722	Osaki et al;	11/1988
	65.	US-4,817,850	Wiener-Avenear et al;	04/1989
	66.	US-4,830,264	Bitailou et al;	05/1989
	67.	US-4,840,302	Gardner et al;	06/1989
	68.	US-4,855,809	Malhi et al;	08/08/1989
	69.	US-4,878,611	LoVasco et al;	02/1989
	70.	US-4,893,403	Heflinger et al;	01/1990
	71.	US-4,897,508	Mahulikar et al;	01/1990
	72.	US-4,897,918	Osaka et al;	02/1990
	73.	US-4,927,505	Sharma et al;	05/1990
	74.	US-4,931,410	Tokanaga et al;	06/1990
	75.	US-4,940,181	Juskey, Jr. et al;	07/1990
	76.	US-4,948,754	Kondo et al;	08/14/1990
	77.	US-4,950,623	Dishon	08/1990
	78.	US-4,962,058	Cronin et al;	10/09/1990
	79.	US-4,972,988	Ohdate	11/1990
	80.	US-5,019,943	Fassbender	05/1991
	81.	US-5,022,580	Pedder	06/1991
	82.	US-5,024,372	Altman et al;	06/1991
	83.	US-5,046,161	Takada	09/1991
	84.	US-5,048,747	Clark et al;	09/1991
	85.	US-5,113,314	Wheeler et al;	05/12/1992
	86.	US-5,130,779	Agarwala et al;	07/1992
	87.	US-5,135,155	Kang et al;	08/1992
	88.	US-5,145,532	Fukunaga et al;	09/08/1992
	89.	US-5,147,084	Behun et al.	09/15/1992
	90.	US-5,152,451	Derveaux et al;	10/1992
	91.	US-5,154,341	Melton et al;	10/1992
	92.	US-5,160,409	Moore et al;	11/1992
	93.	US-5,162,257	Yung	11/1992
	94.	US-5,171,711	Tobimatsu et al.	12/15/1992
	95.	US-5,194,137	Moore et al;	03/1993
	96.	US-5,216,280	Tanaka et al;	06/01/1993
	97.	US-5,227,664	Toshio	07/1993
	98.	US-5,234,149	Katz et al;	08/1993
	99.	US-5,239,447	Cotues et al;	08/1993
	100.	US-5,240,881	Cayetano et al;	08/1993
AM	101.	US-5,250,843	Eichelberger	10/05/1993

Examiner Signature		Date Considered	04/21/2006
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			Examiner Name	Michael Aboagye
(use as many sheets as necessary)			Attorney Docket Number	9180-10CT
Sheet	3	of	7	

AM	102.	US-5,251,806		Agarwala et al.	10/12/1993
	103.	US-5,289,925		Newmark	03/1994
	104.	US-5,293,006		Yung	03/1994
	105.	US-5,325,265		Turlik et al;	06/1994
	106.	US-5,327,013		Moore et al;	07/05/1994
	107.	US-5,327,327		Frew et al;	07/05/1994
	108.	US-5,335,795		Chizen	08/1994
	109.	US-5,347,428		Carson et al;	09/13/1994
	110.	US-5,354,711		Heitzmann et al;	10/11/1994
	111.	US-5,381,946		Koopman et al.	01/17/95
	112.	US-5,391,514		Gall et al;	02/1995
	113.	US-5,406,701		Pepe et al;	04/18/1995
	114.	US-5,409,862		Wada, et al;	04/25/1995
	115.	US-5,424,920		Miyake	06/13/1995
	116.	US-5,432,729		Carson et al;	07/11/1995
	117.	US-5,453,582		Amano et al;	09/26/1995
	118.	US-5,470,787		Greer	11/1995
	119.	US-5,475,280		Jones et al;	12/1995
	120.	US-5,492,235		Crafts et al;	02/1996
	121.	US-5,539,186		Abrami et al.	07/23/1996
	122.	US-5,542,174		Chiu	08/06/1996
	123.	US-5,547,740		Higdon et al;	08/1996
	124.	US-5,551,627		Leicht et al.	09/1996
	125.	US-5,553,769		Ellerson et al.	09/10/1996
	126.	US-5,557,502		Bannerjee et al;	09/1996
	127.	US-5,609,287		Izuta et al.	03-1997
	128.	US-5,616,962		Ishikawa et al;	04/01/1997
	129.	US-5,627,396		James et al;	05/1997
	130.	US-5,634,268		Dalal et al;	06/1997
	131.	US-5,680,296		Hileman et al;	10/1997
	132.	US-5,736,456		Akram	04/1998
	133.	US-5,739,053		Kawakita et al;	04/1998
	134.	US-5,744,382		Kitayama et al;	04/1998
	135.	US-5,751,556		Butler et al;	05/1998
	136.	US-5,773,359		Mitchell et al;	06/1998
	137.	US-5,793,116		Rinne et al;	08/11/1998
	138.	US-5,796,168		Datta et al.	08-18-1998
	139.	US-5,796,591		Dalal et al.	08/18/1998
	140.	US-5,812,378		Fielstad et al;	09/1998
	141.	US-5,851,911		Farnworth	12/1998
	142.	US-5,859,470		Ellerson et al.	01/12/1999
	143.	US-5,886,393		Merrill et al;	03/1999
	144.	US-5,891,756		Erickson et al.	04/06/1999
	145.	US-5,892,179		Rinne et al;	04/1999
	146.	US-5,898,574		Tan et al;	04/1999
	147.	US-5,902,686		Mis	05/1999
	148.	US-5,906,312		Zakel et al.	05/25/1999
	149.	US-5,920,125		Ellerson et al.	07/06/1999
	150.	US-5,923,539		Matsui et al;	07/1999
	151.	US-5,937,320		Andricacos et al;	08/1999
	152.	US-5,963,793		Rinne et al;	10/05/1999
	153.	US-5,990,472		Rinne	11/1999
AM	154.	US-6,027,957		Merritt et al.	02/2000

Examiner Signature		Date Considered	04/21/2008
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			Group Art Unit	1725
			Examiner Name	Michael Aboagye
(use as many sheets as necessary)			Attorney Docket Number	9180-10CT
Sheet	4	of	7	

AM	155.	US-6,083,773		Lake	07/04/2000
	156.	US-6,117,299		Rinne et al.	09/12/00
	157.	US-6,121,069		Boyko et al.	09/19/2000
	158.	US-6,121,576		Hembree et al;	09/2000
	159.	US-6,133,065		Akram	10/2000
	160.	US-6,134,120		Baldwin	10/2000
	161.	US-6,162,652		Dass et al.	12-2000
	162.	US-6,169,325		Azuma	01/2001
	163.	US-6,208,018		Ma et al;	03/2001
	164.	US-6,221,682		Danziger et al;	04/2001
	165.	US-6,222,279		Mis et al;;	04/2001
	166.	US-6,224,690		Andricacos et al.	05-01-2001
	167.	US-6,231,743		Etherington	05/15/2001
	168.	US-6,241,145		Maeda et al;	06/2001
	169.	US-6,281,106		Higdon et al	08/28/2001
	170.	US-6,320,262		Murakami	11/20/2001
	171.	US-6,329,608		Rinne et al.	12-11-2001
	172.	US-6,335,104		Sambucetti et al;	01/2002
	173.	US-6,346,469		Greer	02/12/2002
	174.	US-6,388,203		Rinne et al;	05/14/2002
	175.	US-6,388,203		Rinne et al.	05-14-2002
	176.	US-6,389,691		Rinne et al.	05-21-2002
	177.	US-6,392,163		Rinne et al;	05/21/2002
	178.	US-6,415,974		Jao	07/2002
	179.	US-6,418,033		Rinne	07/09/2002
	180.	US-6,419,974		Silva et al;	07/2002
	181.	US-6,440,291		Henri et al.	08/27/2002
	182.	US-6,441,487		Elenius et al;	08/2002
	183.	US-6,452,270		Huang	09/2002
	184.	US-6,452,271		Jiang et al;	09/2002
	185.	US-6,492,197		Rinne	12/2002
	186.	US-6,495,018		Lowe	12/17/2002
	187.	US-6,521,996		Seshan	02/18/2003
	188.	US-6,620,722		Kuo et al;	09/2003
	189.	US-6,622,907		Fanti et al.	09/2003
	190.	US-6,668,449		Rumsey et al;	12/2003
	191.	US-6,762,122		Mis et al;	07/2004
	192.	US-6,793,792		Jones et al.	08/21/2004
	193.	US-6,835,643		Akram	12/2004
AM	194.	US-6,853,076		Datta et al.	02/2005

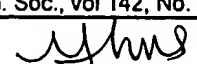
FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Office	Number	Kind Code (if known)		
AM	195.	CN	1269607		English Abstract	01/03/2002
	196.	DE	42 05 029 C		Germany	02/1993
	197.	DE	197 41 436		Germany	12/1998
	198.	DE	43 23 799 A1		Germany	01/1994
	199.	DE	0 782 191 A2		German	12/1996
AM	200.	EP	0 609 062 A1		Europe	08/1994

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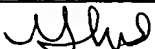
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	202.	EP	1 146 552		Agere Systems Guardian Corporation	10/17/2001	
	203.	EP	0 355 478		International Business Machines Corporation	02-28-1990	
	204.	EP	0 603 296		European	06/1994	
	205.	EP	0 782 191 A2		European	02/1997	
	206.	EP	0 757 386	A2		02/1997	
	207.	EP	0 736 972 A1		Europe	10/1996	
	208.	FR	2 406 893		France	10/1978	Abstract
	209.	FR	2 688 628		France	09/1993	Abstract
	210.	FR	2 705 832		France	12/1994	Abstract
	211.	GB	2 194 387		Great Britain	03/1988	
	212.	GB	2062 963		Great Britain	05/1981	
	213.	GB	1288564		Great Britain	09/1972	
	214.	JP	07-226400			08/1995	Abstract
	215.	JP	63-222445		Japan	09/1988	Abstract
	216.	JP	57-197838		Japan	12/1982	Abstract
	217.	JP	59-154041		Japan	09/1984	Abstract
	218.	JP	4-150033		Japan	05/1992	Abstract
	219.	JP	04-133330			05/1992	Abstract
	220.	JP	54-128669		Japan	10/05/1979	Abstract
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	222.	JP	55-111127		Japan	08/1980	Abstract
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	225.	JP	54050269			04-1979	Abstract
	226.	JP	63099558		Japan	04/1988	Abstract
	227.	JP	2000349111		Fujitsu, Ltd.	12-15-2000	Abstract
	228.	JP	2002203868		Toshiba Corp	07-19-2002	Abstract
	229.	WO	02/03461		Intel Corporation	01/10/2002	
	230.	WO	96/31905		PCT	10/1996	
	231.	WO	96/30933		WIPO	10/1996	
	232.	WO	93/22475		PCT	11/1993	
	233.	WO	98/06118		PCT	02/1998	
	234.	WO	97/03465			01/1997	Abstract
AM	235.	WO	93/02831		PCT	02/1993	

OTHER NON PATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T	
AM	236.	Adema et al., <i>Flip Chip Technology: A Method for Providing Known Good Die with High Density Interconnections</i> , MCM '94 Proceedings, pp. 41-49.		
	237.	Arai et al. "Sn-Ag Solder Bump Formation for Flip-Chip Bonding by Electroplating" <i>Journal of the Electrochemical Society</i> 150(10): c730-c734 (2003)		
	238.	Audet, et al; <i>Low Cost Bumping Process for Flip Chip</i> , Proc. 1995 International Flip Chip, BGA, and Ado Pkg. Symposium ITAP 95, '95 Flip Chip, BGA, TAB & AP Symposium, pp 16-21 (1995).		
	239.	Chan "Investigation of Cr/Cu/Cu/Ni Under Bump Metallization for Lead-free Applications" 2002 <i>Electronics Packaging Technology Conference</i> 270-275 (2002)		
	240.	Choi et al; <i>Electromigration of Flip Chip Solder Bump on Cu/Ni(V) A1 Thin Film Under Bump Metallization</i> ; 2002 Electronic Components and Technology Conference; pp 1201-1205.		
AM	241.	Datta, et al., <i>Electrochemical Fabrication of Mechanically Robust PbSn C4 Interconnections</i> , J. Electrochem. Soc., vol 142, No. 11, pp 3779-3785 (Nov. 1995).		
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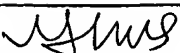
AM	242.	Drake et al; <i>An Electrostatically Actuated Micro-Relay</i> , Transducers '95, Eurosensors IX, The 8 th International Conference on Solid-State Sensors and Actuators, and Eurosensors IX, pp 380-383.	
	243.	Edelstein, D.C., et al; Derwent Publications Ltd. London, GB: AN 2002-308284 XP-002243726.	
	244.	Ezawa et al. "Eutectic Sn-Ag Solder Bump Process for ULSI Flip Chip Technology" <i>IEEE Transactions on Electronics Packaging Manufacturing</i> 24(4): 275-281 (2001)	
	245.	Ezawa et al; <i>Pb-Free Bumping by Alloying Electroplated Metal Stacks</i> ; 2003 Electronic Components and Technology Conference; pp 664-667.	
	246.	Graf "The Modern Dictionary of Electronics" Sixth Edition p. 386 (1984)	
	247.	Greer "An Extended Eutectec Solder bump for FCOB" 1996 <i>Electronic Componets and Technology Conference</i> pp. 546-551 (1996)	
	248.	Guckel et al., <i>Electromagnetic Linear Actuators with Inductive Position Sensing for Micro Relay, Micro Valve and Precision Positioning Applications</i> , Transducers '95, Eurosensors IX, The 8 th International Conference on Solid-State Sensors and Actuators, and Eurosensors IX, pp 324-327.	
	249.	Hashimoto et al; <i>Thermally Controlled Magnetization Microrelay</i> , Transducers '95, Eurosensors IX, The 8 th International Conference on Solid-State Sensors and Actuators, and Eurosensors IX, pp 361-364.	
	250.	Hirsch, <i>Tin-Lead, Lead and Tin Plating</i> , Metal Finishing, Guidebook Directory 1987, 55 th Guidebood-Directory Issue 1987, Mid Jan. 1987, vol. 85, No. 1A, ISSN 0026-0576, pp. 280-284.	
	251.	Hosaka et al; <i>Electromagnetic Microrelays: Concepts and Fundamental Characteristics</i> , Sensors and Actuators A, 40 (1994), pp 41-47.	
	252.	Howell et al; "Area Array Solder Interconnection Technology for the Three-Dimensional Silicon Cube", <i>Proceedings of the 1995 45th Electronic Components & Technology Conference</i> , pp 1174-1178.	
	253.	Inaba et al; <i>Solder Bump Formation Using Electroless Plating and Ultrasonic Soldering</i> , IEEE Transactions On Components, Hybrids, and Manufacturing Technology, vol. 13, No. 1, Mar. 1990, pp. 119-123.	
	254.	International Search Report and Written Opinion of the International Searching Authority for International patent application no. PCT/US2005/023041 mailed on October 11, 2005	
	255.	International Search Report and Written Opinion of the International Searching Authority for International Application no. PCT/US2005/012029 mailed on October 28, 2005	
	256.	International Search Report dated Dec. 9, 1992 of International Application. No. PCT/US 92/07722	
	257.	International Search Report for PCT/US 02/30697 mailed on June 24, 2003	
	258.	International Search Report for PCT/US 03/20790 mailed on June 2, 2004	
	259.	International Search Report for PCT/US2001/14674 mailed on January 23, 2002	
	260.	International Search Report, PCT/US01/43948 April 1, 2003	
	261.	Invitation to Pay Additional Fees and Partial International Search Report for International patent application no. PCT/US2005/012029 mailed on July 26, 2005	
	262.	Jung, et al., <i>The Influence of NiSn Intermetallics on the Performance of Flip Chip Contacts Using a Low Cost Electroless Nickel Bumping Approach</i> , IEPS Proceedings of the Technical Conference, 1996 Electronics Packaging Conference, Austin, Texas, pp 14-25 (Sep. 29-Oct. 1, 1996).	
	263.	Kang, et al; <i>Interfacial Reactions During Soldering With Lead-Tin Eutectic and Lead (Pb)-Free, Tin-Rich Solders</i> , <i>Journal of Electronic Materials</i> , vol 25, No. 7, pp 1113-1120 (1996).	
	264.	Kim et al. "Electrodeposition of Near-Eutectic SnAg Solders for Wafer-Level Packaging" <i>Journal of The Electrochemical Society</i> 150(9): c577-c584 (2003)	
	265.	Kiumi et al. "Processing, Properties, and reliability of electroplated Lead-Free Solder Bumps" <i>IEEE 2002 Inter Society Conference on Thermal Phenomena</i> pp. 909-914 (2002)	
	266.	Knüppel, <i>Rugged Design for Reliable Switching: Micro a Relay Sets New Automotive Standards</i> , Components XXIX (1994), No. 4, pp 30-32.	
	267.	Lineback, "3D IC Packaging Moves Closer to Commercial Use", <i>Electronic World News</i> , May 21, 1990, p 15.	
	268.	Mis, et al; <i>Flip Chip Production Experience: Some Design, Process, Reliability, and Cost Considerations</i> , ISHM '96 Proceedings, Proc. 1996 International Symposium on Microelectronics SPIE vol. 2920, pp 291-295 (1996).	
	269.	Multimedia Card Association, www.mmca.org .	
	270.	PCB Assembly, <i>Electronic Packaging & Production</i> , vol. 35, No. 1, p. 40 (Jan. 1995).	
AM	271.	SanDisk Corporation, SanDisk Flash Data Storage, San Disk Compact Flash™ and MultiMedia Card:	

Examiner Signature		Date Considered	04/21/2006
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Substitute form 1449A/PTO		Complete if Known			
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Application Number	10/790,967		
		Filing Date	March 2, 2004		
		First Named Inventor	Glenn A. Rinne		
		Group Art Unit	1725		
		Examiner Name	Michael Aboagye		
Sheet	7	of	7	Attorney Docket Number	9180-10CT

AN		Small Form Factor Solutions, 1999.	
	272.	Solomon "Providing high Density and Performance for Chip-to Sytem Interconnection" <i>Advanced Packaging</i> (Nov 2001) pp. 19-28	
	273.	Specification Sheet, <i>NaiS, Ultra Low Profile 2 Amp-Polarized Relay</i> , TK-Relays.	
	274.	Tessier et al; <i>Process Considerations in Fabricating Thin Film Multi-chip Modules</i> , Proceedings of the Technical Conference 1989 International Electronics Packaging Conference, 1989.	
	275.	Yung et al. "Flip-Chip Process Utilizing Electroplated Solder Joints" <i>Proceedings of the Technical Conference</i> (Sep 10-12, 1990) International Electronics Packaging Conference Malborough, Massachusetts pp. 1065-1073	
	276.	Yung et al; <i>Electroplated Solder Joints for Flip-Chip Applications</i> , Transactions on Components, Hybrids, and Manufacturing Technology, vol. 14 No. 3, Sep. 1991, pp 549-559.	
DM	277.	Zeng et al; <i>Six cases of reliability study of Pb-free solder joints in electronic packaging technology</i> , Reports: A Review Journal; Materials Science and Engineering R 38 (2002) pp 55-105.	

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